ABSTRACT

The present invention is a cooling device for removing heat from an integrated circuit. In one embodiment, the cooling device includes a conduit and a flexible channel having a first open end and a second closed end. The flexible channel's first open end has an internal width and is coupled with the conduit. The flexible channel is comprised of a resilient material having spring-like characteristics. In one embodiment, this material provides a spring-like restoring force when compressed. The cooling device also includes an interconnect mechanism between the conduit and the flexible channel to allow a gas or a fluid introduced within the conduit to move between the conduit and the flexible channel.